Abstract

The outer face of a case which accommodates a whole microphone is coated by a material having a heat conductivity which is lower than that of a metal, and a material transforming temperature which is higher than the charge dissipating temperature of a dielectric layer for forming an internal electret, and which is higher than 260°C, so that the internal temperature rise can be mitigated by the thermal resistance and the thermal capacity of the whole interior. When a microphone is attached to an application equipment, particularly, the microphone may be passed through a reflow solder bath for a short time period. A heat-resistant structure which can prevent the function from being impaired by a high temperature in the period is provided.